

BOX CLAMPS Series BX59LP

DESCRIPTION

GD Rectifiers Ltd produce a range of large disc cell clamping devices, specially developed for single side applications of commonly used press pack semiconductors.

Suitable for single side cooling of devices, and some rotating applications.

Materials and components used in the manufacturing of these clamps are carefully selected and quality controlled, to ensure the compliance with the requested specifications.

BX59LP "Low Profile" series are supplied with a specific preset clamping force, to allow an easy and accurate clamping with no special tools.

Suitable for semiconductor thickness 26mm Nom, clamping force 12kN.

Busbar 3 to 3.175mm thick.

HOW TO ORDER

BX59LP – (3) – (12) – (26),

Where X specifies, Busbar connection thickness (mm), Y the calibration force (kN), and Z, the cell height (mm). E.g. BX59LP-3-12-26

TECHNICAL CHARACTERISTICS

Dimensions see figures below, Clamping force 12 kN \pm 10%

Insulation Material Noryl, Operating Temp. Range -30°C - +110°C. Storage -40°C - +110°C

Dielectric Strength 6kV+ rms 50Hz

Semiconductor Diameter 59mm max. Semiconductor Thickness 26mm Nom.

Weight 200g approx. Fixing Screws not supplied with Clamp.

Special designs are available on request; please contact GD Rectifiers Ltd for details.

